

ULTRA RUGGED I/O SYSTEMS (1.00 mm) .0394" PITCH

FEATURES & BENEFITS

- **2.9**
- Small form factor
- Four points of contact for a reliable connection and high mating cycles
- Up to 40 positions per row
- Cable-to-cable & cable-to-board solutions
- EMI shielding limits signal degradation and optimizes performance
- Through-hole or surface mount
- 28 & 30 AWG cable



Shown actual size at 20 total positions

Hyperboloid-type contact for extreme high mating cycles



Extreme density with up to 1,450 total I/Os in a 1RU panel (29 cables at 50 total I/Os each)

KEY SPECIFICATIONS (P1PD(X), B1SD(X) & P1M)

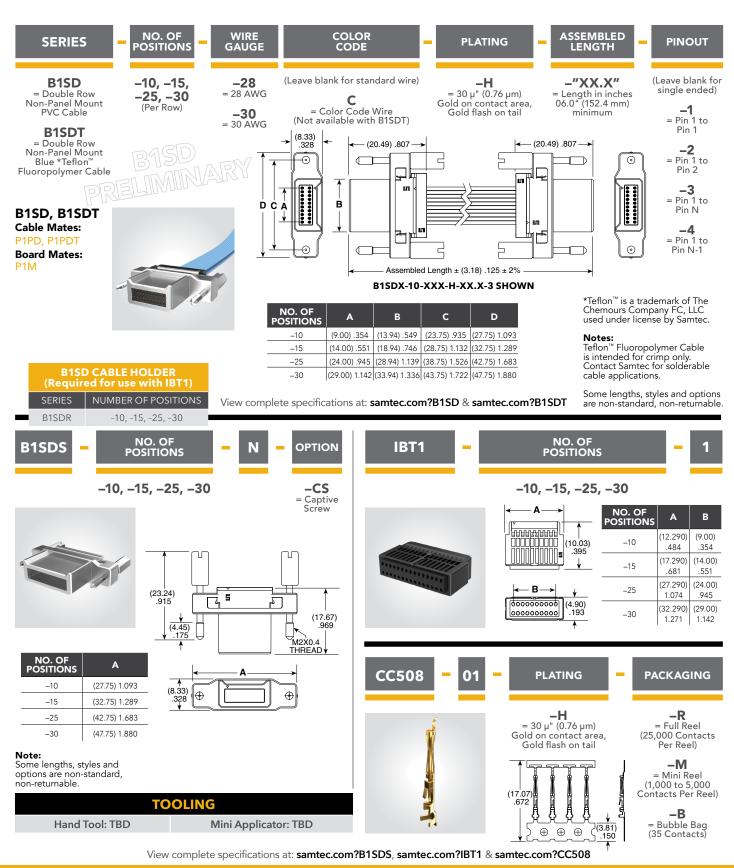
РІТСН	INSULATOR MATERIAL	CONTACT MATERIAL	SHIELD MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING
1.00 mm	Liquid Crystal Polymer	Beryllium Copper	Zinc Alloy	Au over 50 μ" (1.27 μm) Ni	–10 °C to +80 °C (PVC) –40 °C to +125 °C (*Teflon™ Fluoropolymer)	2.9 A per pin (2 pins powered)	253 VAC
*Teflon™ is a trademark of The Chemours Company FC, LLC used under license by Samtec.							

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.





(1.00 mm) .0394" PITCH • NON-PANEL MOUNT I/O CABLE/COMPONENTS



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